

**AMENDMENT OF THE SPECIFICATION**

Page 1, after the title of the invention and before the beginning of the first paragraph, please insert the following title:

**B<sup>1</sup>**  
**--BACKGROUND OF THE INVENTION--**

Page 1, line 28 (beginning of last paragraph), through Page 2, line 5, please amend this paragraph as follows:

**B<sup>2</sup>**  
DE 44 33 845 A1 discloses a method for producing a three-dimensional integrated circuit wherein two finished substrates or single circuits are interconnected. For vertical electric connection of the circuits contained on both substrates, further process steps are performed to produce a metalization after connecting the two substrates one of which was thinned. The disadvantage of the known method is that completely processed substrates must be made available and additional process steps are required for producing the vertical electric connection.

Page 2, between lines 9 and 10, please insert the following title:

**B<sup>3</sup>**  
**--SUMMARY OF THE INVENTION--**

Page 2, line 12, please delete this paragraph in its entirety as follows:

~~This problem is solved by the features of the independent claims.~~

Application No.: 09/926,377  
Examiner: David L. HOGANS  
Art Unit: 2813

Page 2, between lines 21 and 22, please insert the following title:

B4

--BRIEF DESCRIPTION OF THE DRAWINGS--

Page 2, between lines 27 and 28, please insert the following title:

B5

--DETAILED DESCRIPTION OF THE INVENTION--